



Welcome to [E-XFL.COM](#)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10000
Total RAM Bits	221184
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp10c-5f256c

Introduction

The LatticeXP family of FPGA devices combine logic gates, embedded memory and high performance I/Os in a single architecture that is both non-volatile and infinitely reconfigurable to support cost-effective system designs.

The re-programmable non-volatile technology used in the LatticeXP family is the next generation ispXP™ technology. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. In addition, instant-on capability allows for easy interfacing in many applications.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeXP family of FPGA devices. Synthesis library support for LatticeXP is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeXP device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeXP family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

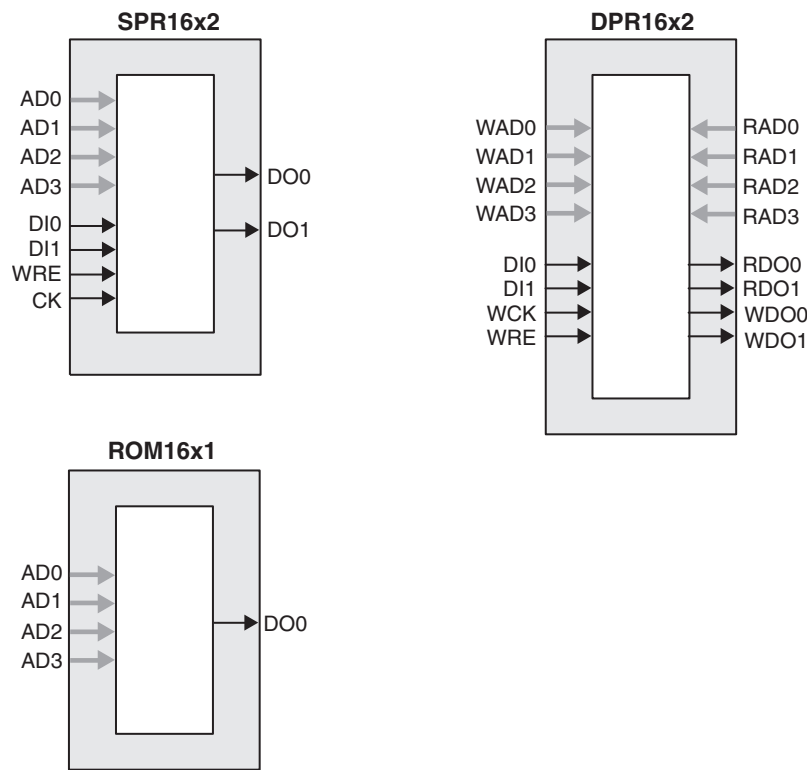
The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-4 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode in LatticeXP devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required for Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Figure 2-4. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

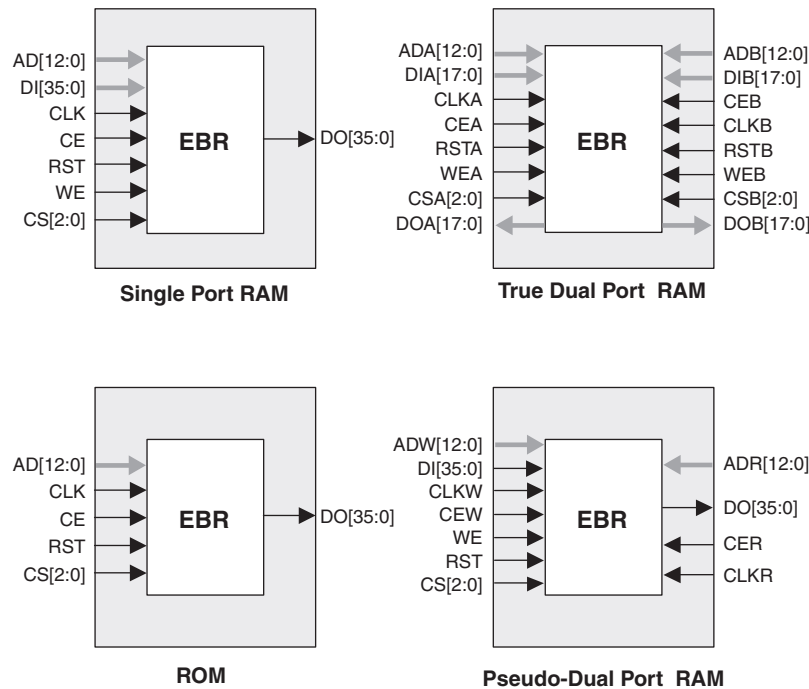
If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAMs can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

Figure 2-14 shows the four basic memory configurations and their input/output names. In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

Figure 2-14. sysMEM Memory Primitives

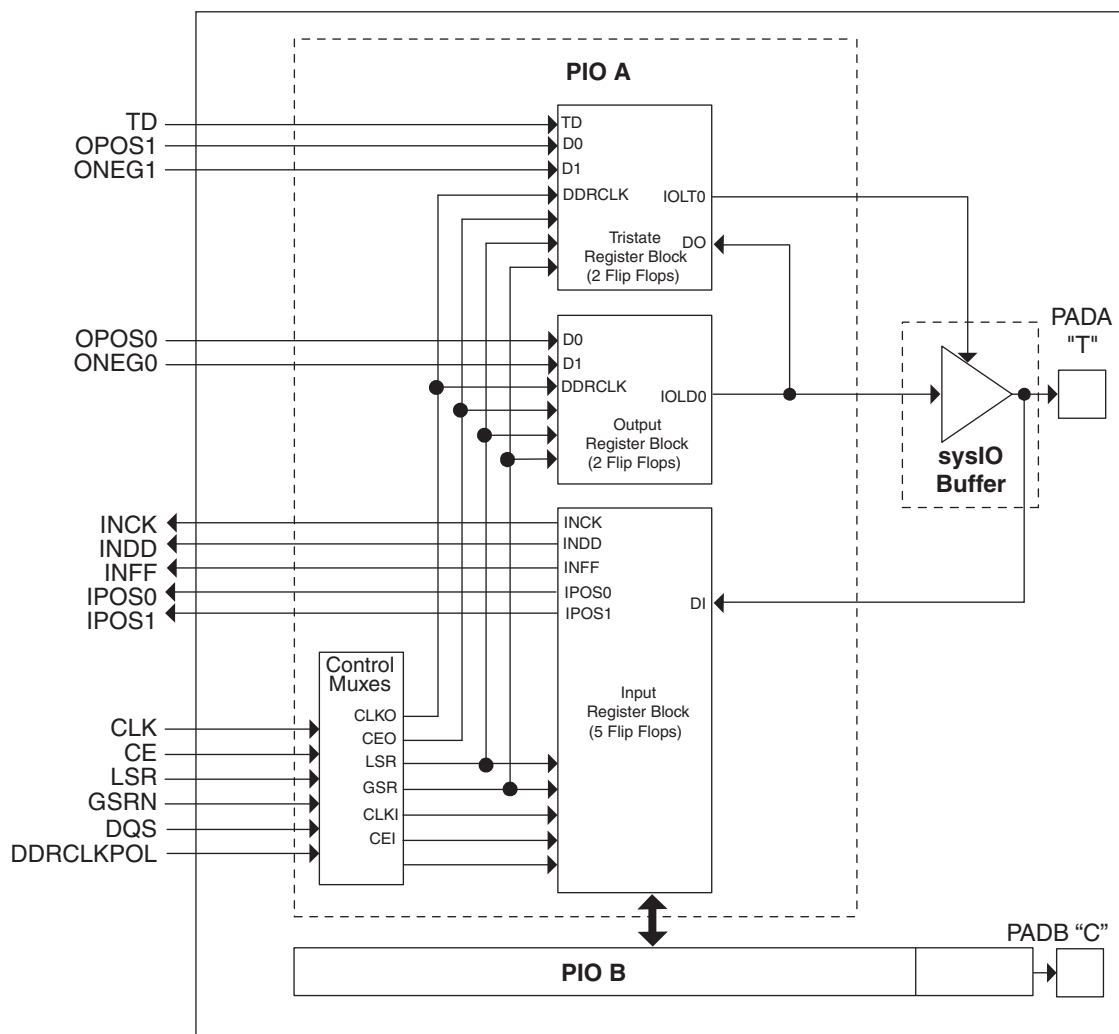
The EBR memory supports three forms of write behavior for single port or dual port operation:

1. **Normal** – data on the output appears only during read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port during a write cycle. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old content of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-15.

Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeXP family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of the each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysIO Buffer Banks

LatticeXP devices have eight sysIO buffer banks; each is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-28 shows the eight banks and their associated supplies.

In the LatticeXP devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using V_{CCIO} . LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as a fixed threshold input independent of V_{CCIO} . In addition to the bank V_{CCIO} supplies, the LatticeXP devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeXP devices, a dedicated pin in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,2,4}$	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
		$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	40	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-150	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	150	μA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	-150	μA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
C1	I/O Capacitance ³	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	8	—	pf
C2	Dedicated Input Capacitance ³	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. Not applicable to SLEEPN/TOE pin.

3. $T_A = 25^\circ C$, $f = 1.0MHz$

4. When V_{IH} is higher than V_{CCIO} , a transient current typically of 30ns in duration or less with a peak current of 6mA can be expected on the high-to-low transition.

Supply Current (Sleep Mode)^{1, 2, 3}

Symbol	Parameter	Device	Typ. ⁴	Max	Units
I_{CC}	Core Power Supply	LFXP3C	12	65	μA
		LFXP6C	14	75	μA
		LFXP10C	16	85	μA
		LFXP15C	18	95	μA
		LFXP20C	20	105	μA
I_{CCP}	PLL Power Supply (per PLL)	All LFXP 'C' Devices	1	5	μA
I_{CCAUX}	Auxiliary Power Supply	LFXP3C	2	90	μA
		LFXP6C	2	100	μA
		LFXP10C	2	110	μA
		LFXP15C	3	120	μA
		LFXP20C	4	130	μA
I_{CCIO}	Bank Power Supply ⁵	LFXP3C	2	20	μA
		LFXP6C	2	22	μA
		LFXP10C	2	24	μA
		LFXP15C	3	27	μA
		LFXP20C	4	30	μA
I_{CCJ}	VCCJ Power Supply	All LFXP 'C' Devices	1	5	μA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency 0MHz.

3. User pattern: blank.

4. $T_A = 25^\circ C$, power supplies at nominal voltage.

5. Per bank.

Supply Current (Standby)^{1, 2, 3, 4}**Over Recommended Operating Conditions**

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LFXP3E	15	mA
		LFXP6E	20	mA
		LFXP10E	35	mA
		LFXP15E	45	mA
		LFXP20E	55	mA
		LFXP3C	35	mA
		LFXP6C	40	mA
		LFXP10C	70	mA
		LFXP15C	80	mA
		LFXP20C	90	mA
I_{CCP}	PLL Power Supply (per PLL)	All	8	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LFXP3E/C	22	mA
		LFXP6E/C	22	mA
		LFXP10E/C	30	mA
		LFXP15E/C	30	mA
		LFXP20E/C	30	mA
I_{CCIO}	Bank Power Supply ⁶	All	2	mA
I_{CCJ}	V_{CCJ} Power Supply	All	1	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

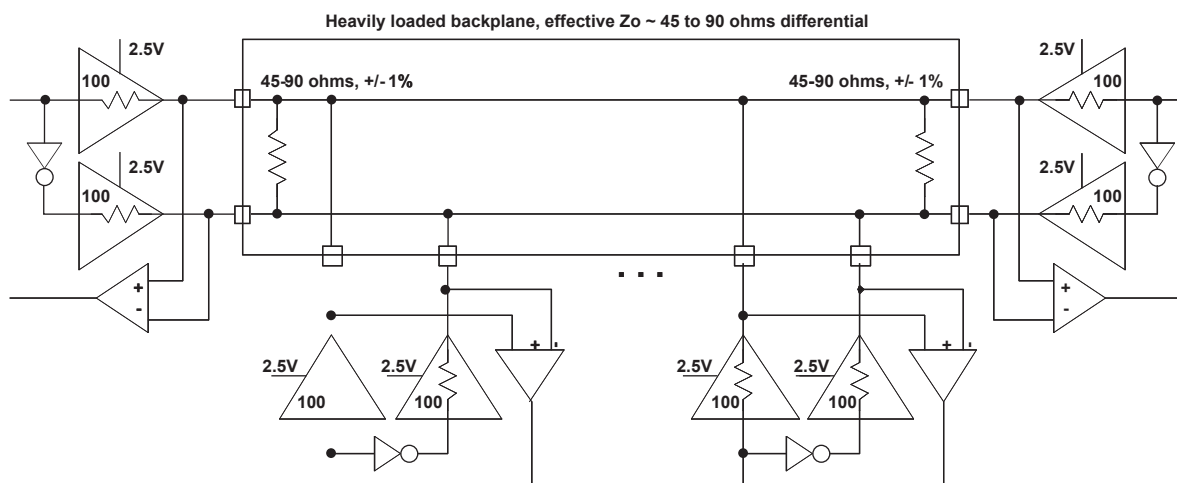
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the VCCIO or GND.

3. Frequency 0MHz.

4. User pattern: blank.

5. $T_A=25^{\circ}C$, power supplies at nominal voltage.

6. Per bank.

Figure 3-2. BLVDS Multi-point Output Example**Table 3-2. BLVDS DC Conditions¹****Over Recommended Operating Conditions**

Symbol	Description	Typical		Units
		Zo = 45	Zo = 90	
Z _{OUT}	Output impedance	100	100	ohms
R _{TLEFT}	Left end termination	45	90	ohms
R _{TRIGHT}	Right end termination	45	90	ohms
V _{OH}	Output high voltage	1.375	1.48	V
V _{OL}	Output low voltage	1.125	1.02	V
V _{OD}	Output differential voltage	0.25	0.46	V
V _{CM}	Output common mode voltage	1.25	1.25	V
I _{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LatticeXP Family Timing Adders¹ (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.8	0.8	0.8	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.5	0.5	0.5	ns
LVTTTL33_12mA	LVTTTL 12mA drive	0.3	0.3	0.3	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.4	0.4	0.4	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.3	0.3	0.3	ns
LVC MOS33_2mA	LVC MOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVC MOS25_2mA	LVC MOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVC MOS18_2mA	LVC MOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVC MOS15_2mA	LVC MOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVC MOS 2.5, 12mA.
Timing v.F0.11

LatticeXP sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	3	—	ns
t_{CODO}	Clock to Dout in Flowthrough Mode	—	12	ns
t_{SUCS}	CS[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CS[0:1] Hold Time to CCLK	2	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	2	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	Clock to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave Clock Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave Clock Minimum Low Pulse	8	—	ns
t_{BSCYC}	Byte Slave Clock Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI (Data In) Setup Time to CCLK	7	—	ns
t_{HSCDI}	DI (Data In) Hold Time to CCLK	2	—	ns
t_{CODO}	Clock to Dout in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave Clock Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave Clock Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake Up				
t_{ICFG}	Minimum Vcc to INIT High	—	50	ms
t_{VMC}	Time from t_{ICFG} to Valid Master Clock	—	2	us
t_{PRGMRJ}	Program Pin Pulse Rejection	—	7	ns
t_{PRGM}^2	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	INIT Low Time	—	1	ms
t_{DPPINIT}	Delay Time from PROGRAMN Low to INIT Low	—	37	ns
t_{DINITD}	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	25	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after Done Pin High	120	—	cycles
Configuration Master Clock (CCLK)				
Frequency ¹		Selected Value - 30%	Selected Value + 30%	MHz
Duty Cycle		40	60	%

1. See Table 2-10 for available CCLK frequencies.

2. The threshold level for PROGRAMN, as well as for CFG[1] and CFG[0], is determined by V_{CC} , such that the threshold = $V_{CC}/2$.
Timing v.F0.11

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
139	PT6A	0	-	DI	PT9A	0	-	DI
140	PT5A	0	-	CSN	PT8A	0	-	CSN
141	PT3B	0	-	VREF2_0	PT6B	0	-	VREF2_0
142	CFG0	0	-	-	CFG0	0	-	-
143	CFG1	0	-	-	CFG1	0	-	-
144	DONE	0	-	-	DONE	0	-	-

1. Applies to LFXP "C" only.
2. Applies to LFXP "E" only.
3. Supports dedicated LVDS outputs.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E8	PT13B	0	-	-	PT17B	0	-	-
D8	PT12A	0	-	DOUT	PT16A	0	-	DOUT
A6	PT11B	0	C	-	PT15B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	PT11A	0	T	WRITEN	PT15A	0	T	WRITEN
E7	PT10B	0	C	-	PT14B	0	C	-
D7	PT10A	0	T	VREF1_0	PT14A	0	T	VREF1_0
A5	PT9B	0	C	-	PT13B	0	C	-
B5	PT9A	0	T	DI	PT13A	0	T	DI
A4	PT8B	0	C	-	PT12B	0	C	-
B6	PT8A	0	T	CSN	PT12A	0	T	CSN
E6	PT7B	0	C	-	PT11B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D6	PT7A	0	T	-	PT11A	0	T	-
D5	PT6B	0	C	VREF2_0	PT10B	0	C	VREF2_0
A3	PT6A	0	T	DQS	PT10A	0	T	DQS
B3	PT5B	0	-	-	PT9B	0	-	-
B2	PT4A	0	-	-	PT8A	0	-	-
A2	PT3B	0	C	-	PT7B	0	C	-
B1	PT3A	0	T	-	PT7A	0	T	-
F5	PT2B	0	C	-	PT6B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT2A	0	T	-	PT6A	0	T	-
C4	CFG0	0	-	-	CFG0	0	-	-
B4	CFG1	0	-	-	CFG1	0	-	-
C3	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A16	GND	-	-	-	GND	-	-	-
F11	GND	-	-	-	GND	-	-	-
F6	GND	-	-	-	GND	-	-	-
G10	GND	-	-	-	GND	-	-	-
G7	GND	-	-	-	GND	-	-	-
G8	GND	-	-	-	GND	-	-	-
G9	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-
H7	GND	-	-	-	GND	-	-	-
H8	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J7	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP "C" only.
2. Applies to LFXP "E" only.
3. Supports dedicated LVDS outputs.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
AA20	PB36B	4	C	-	PB41B	4	C	-	PB45B	4	C	-
AB21	PB37A	4	T	-	PB42A	4	T	-	PB46A	4	T	-
AA21	PB37B	4	C	-	PB42B	4	C	-	PB46B	4	C	-
AA22	PB38A	4	T	-	PB43A	4	T	-	PB47A	4	T	-
Y21	PB38B	4	C	-	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
W16	PB39A	4	-	-	PB44A	4	T	-	PB48A	4	T	-
W17	-	-	-	-	PB44B	4	C	-	PB48B	4	C	-
Y15	-	-	-	-	PB45A	4	-	-	PB49A	4	-	-
Y16	-	-	-	-	PB46B	4	-	-	PB50B	4	-	-
W19	-	-	-	-	PB47A	4	T	DQS	PB51A	4	T	DQS
W18	-	-	-	-	PB47B	4	C	-	PB51B	4	C	-
W20	-	-	-	-	PB48A	4	-	-	PB52A	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
T20	PR35B	3	C ³	-	PR39B	3	C ³	-	PR43B	3	C ³	-
T19	PR35A	3	T ³	-	PR39A	3	T ³	-	PR43A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
U19	PR34B	3	C	RLM0_PLLC_FB_A	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
U20	PR34A	3	T	RLM0_PLLT_FB_A	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
V19	PR33B	3	C ³	-	PR37B	3	C ³	-	PR41B	3	C ³	-
V20	PR33A	3	T ³	DQS	PR37A	3	T ³	DQS	PR41A	3	T ³	DQS
R19	PR32B	3	-	-	PR36B	3	-	-	PR40B	3	-	-
R20	PR31A	3	-	VREF1_3	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
W21	PR30B	3	C ³	-	PR34B	3	C ³	-	PR38B	3	C ³	-
Y22	PR30A	3	T ³	-	PR34A	3	T ³	-	PR38A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
P19	PR29B	3	C	-	PR33B	3	C	-	PR37B	3	C	-
P20	PR29A	3	T	-	PR33A	3	T	-	PR37A	3	T	-
V21	PR28B	3	C ³	-	PR32B	3	C ³	-	PR36B	3	C ³	-
W22	PR28A	3	T ³	-	PR32A	3	T ³	-	PR36A	3	T ³	-
U21	PR26B	3	C ³	-	PR30B	3	C ³	-	PR34B	3	C ³	-
V22	PR26A	3	T ³	-	PR30A	3	T ³	-	PR34A	3	T ³	-
T21	PR25B	3	C	RLM0_PLLC_IN_A	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
U22	PR25A	3	T	RLM0_PLLT_IN_A	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
R21	PR24B	3	C ³	-	PR28B	3	C ³	-	PR32B	3	C ³	-
T22	PR24A	3	T ³	DQS	PR28A	3	T ³	DQS	PR32A	3	T ³	DQS
N19	PR23B	3	-	-	PR27B	3	-	-	PR31B	3	-	-
N20	PR22A	3	-	VREF2_3	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
R22	PR21B	3	C ³	-	PR25B	3	C ³	-	PR29B	3	C ³	-
P22	PR21A	3	T ³	-	PR25A	3	T ³	-	PR29A	3	T ³	-
P21	PR20B	3	C	-	PR24B	3	C	-	PR28B	3	C	-
N21	PR20A	3	T	-	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
M20	PR19B	3	C ³	-	PR23B	3	C ³	-	PR27B	3	C ³	-
M19	PR19A	3	T ³	-	PR23A	3	T ³	-	PR27A	3	T ³	-
N22	GNDP1	-	-	-	GNDP1	-	-	-	GNDP1	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB5	PB16A	5	T	-	PB20A	5	T	-
AB6	PB16B	5	C	-	PB20B	5	C	-
AA8	PB17A	5	T	-	PB21A	5	T	-
AA9	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
W10	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
V10	PB18B	5	C	-	PB22B	5	C	-
AB7	PB19A	5	T	-	PB23A	5	T	-
AB8	PB19B	5	C	-	PB23B	5	C	-
AB9	PB20A	5	T	-	PB24A	5	T	-
AB10	PB20B	5	C	-	PB24B	5	C	-
Y10	PB21A	5	-	-	PB25A	5	-	-
AA10	PB22B	5	-	-	PB26B	5	-	-
W11	PB23A	5	T	DQS	PB27A	5	T	DQS
V11	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y11	PB24A	5	T	-	PB28A	5	T	-
AA11	PB24B	5	C	-	PB28B	5	C	-
AB11	PB25A	5	T	-	PB29A	5	T	-
AB12	PB25B	5	C	-	PB29B	5	C	-
Y12	PB26A	4	T	-	PB30A	4	T	-
AA12	PB26B	4	C	-	PB30B	4	C	-
W12	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
V12	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AB13	PB28A	4	T	-	PB32A	4	T	-
AB14	PB28B	4	C	-	PB32B	4	C	-
AA13	PB29A	4	-	-	PB33A	4	-	-
Y13	PB30B	4	-	-	PB34B	4	-	-
AB15	PB31A	4	T	DQS	PB35A	4	T	DQS
AB16	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
V13	PB32A	4	T	-	PB36A	4	T	-
W13	PB32B	4	C	-	PB36B	4	C	-
AA14	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA15	PB33B	4	C	-	PB37B	4	C	-
AB17	PB34A	4	T	-	PB38A	4	T	-
AB18	PB34B	4	C	-	PB38B	4	C	-
W14	PB35A	4	T	-	PB39A	4	T	-
Y14	PB35B	4	C	-	PB39B	4	C	-
U14	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
V14	PB36B	4	C	-	PB40B	4	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R18	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
R17	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
Y22	PR37B	3	C ³	-	PR41B	3	C ³	-
Y21	PR37A	3	T ³	DQS	PR41A	3	T ³	DQS
W22	PR36B	3	-	-	PR40B	3	-	-
W21	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
P17	PR34B	3	C ³	-	PR38B	3	C ³	-
P18	PR34A	3	T ³	-	PR38A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
R19	PR33B	3	C	-	PR37B	3	C	-
R20	PR33A	3	T	-	PR37A	3	T	-
V22	PR32B	3	C ³	-	PR36B	3	C ³	-
V21	PR32A	3	T ³	-	PR36A	3	T ³	-
U22	PR30B	3	C ³	-	PR34B	3	C ³	-
U21	PR30A	3	T ³	-	PR34A	3	T ³	-
P19	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
P20	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
T22	PR28B	3	C ³	-	PR32B	3	C ³	-
T21	PR28A	3	T ³	DQS	PR32A	3	T ³	DQS
R22	PR27B	3	-	-	PR31B	3	-	-
R21	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
N19	PR25B	3	C ³	-	PR29B	3	C ³	-
N20	PR25A	3	T ³	-	PR29A	3	T ³	-
N18	PR24B	3	C	-	PR28B	3	C	-
M18	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P22	PR23B	3	C ³	-	PR27B	3	C ³	-
P21	PR23A	3	T ³	-	PR27A	3	T ³	-
N22	-	-	-	-	PR26B	3	C ³	-
N21	-	-	-	-	PR26A	3	T ³	-
M19	-	-	-	-	PR25B	3	-	-
M20	GNDP1	-	-	-	GNDP1	-	-	-
L18	VCCP1	-	-	-	VCCP1	-	-	-
M21	-	-	-	-	PR24A	2	-	-
M22	PR22B	2	C ³	-	PR23B	2	C ³	-
L22	PR22A	2	T ³	-	PR23A	2	T ³	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
L19	-	-	-	-	PR22B	2	C ³	-
L20	-	-	-	-	PR22A	2	T ³	-
L21	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K22	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
J15	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K11	GND	-	-	-	GND	-	-	-
K12	GND	-	-	-	GND	-	-	-
K13	GND	-	-	-	GND	-	-	-
K14	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L10	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L12	GND	-	-	-	GND	-	-	-
L13	GND	-	-	-	GND	-	-	-
L14	GND	-	-	-	GND	-	-	-
L9	GND	-	-	-	GND	-	-	-
M10	GND	-	-	-	GND	-	-	-
M11	GND	-	-	-	GND	-	-	-
M12	GND	-	-	-	GND	-	-	-
M13	GND	-	-	-	GND	-	-	-
M14	GND	-	-	-	GND	-	-	-
M9	GND	-	-	-	GND	-	-	-
N10	GND	-	-	-	GND	-	-	-
N11	GND	-	-	-	GND	-	-	-
N12	GND	-	-	-	GND	-	-	-
N13	GND	-	-	-	GND	-	-	-
N14	GND	-	-	-	GND	-	-	-
N9	GND	-	-	-	GND	-	-	-
P10	GND	-	-	-	GND	-	-	-
P11	GND	-	-	-	GND	-	-	-
P12	GND	-	-	-	GND	-	-	-
P13	GND	-	-	-	GND	-	-	-
P14	GND	-	-	-	GND	-	-	-
P15	GND	-	-	-	GND	-	-	-
P8	GND	-	-	-	GND	-	-	-
P9	GND	-	-	-	GND	-	-	-
R14	GND	-	-	-	GND	-	-	-
R9	GND	-	-	-	GND	-	-	-
F10	VCC	-	-	-	VCC	-	-	-
F13	VCC	-	-	-	VCC	-	-	-
G10	VCC	-	-	-	VCC	-	-	-
G13	VCC	-	-	-	VCC	-	-	-
G14	VCC	-	-	-	VCC	-	-	-

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4F484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3F388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4F388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3F256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4F256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4F484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3F388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4F388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3F256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4F256I	188	1.2V	-4	fpBGA	256	IND	19.7K

Lead-free Packaging**Commercial**

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3QN208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4QN208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5QN208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3TN144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4TN144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5TN144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3TN100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4TN100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5TN100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3QN208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4QN208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5QN208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3TN144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4TN144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5TN144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3FN388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4FN388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5FN388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3FN484C	300	1.8/2.5/3.3V	-3	fpBGA	484	COM	15.5K
LFXP15C-4FN484C	300	1.8/2.5/3.3V	-4	fpBGA	484	COM	15.5K
LFXP15C-5FN484C	300	1.8/2.5/3.3V	-5	fpBGA	484	COM	15.5K
LFXP15C-3FN388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	15.5K
LFXP15C-4FN388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	15.5K
LFXP15C-5FN388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	15.5K
LFXP15C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	15.5K
LFXP15C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	15.5K
LFXP15C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	15.5K